LNJ611W8WRA

Hight Bright Surface Mounting Chip LED

3216 Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P _D	40	mW	
Forward current	I _F	10	mA	
Pulse forward current *	I _{FP}	40	mA	
Reverse voltage	V _R	5	V	
Operating ambient temperature	T _{opr}	-25 to +85	°C	
Storage temperature	T _{stg}	-30 to +100	°C	

Lighting Color

• Pure Green

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

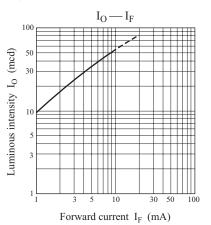
Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *	I _O	$I_{\rm F} = 5 {\rm mA}$	14.4	34.0		mcd
Reverse current	I _R	$V_R = 5 V$			10	μΑ
Forward voltage	V _F	$I_F = 5 \text{ mA}$		3.0	3.7	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 5 {\rm mA}$		525		nm
Spectral half band width	Δλ	$I_{\rm F} = 5 {\rm mA}$		45		nm

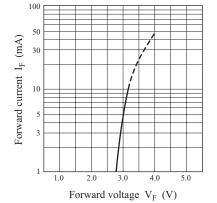
 I_F

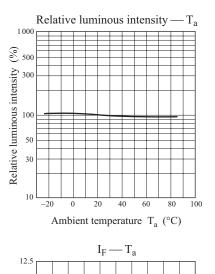
VF

Note) *: Measurement tolerance: ±20%



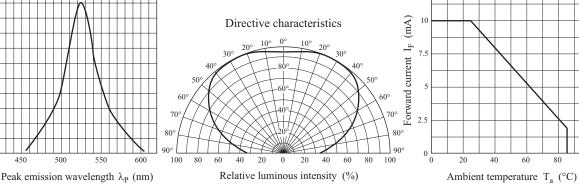
Relative luminous intensity — λ_P





60

80



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450

Relative luminous intensity (%)

80

40

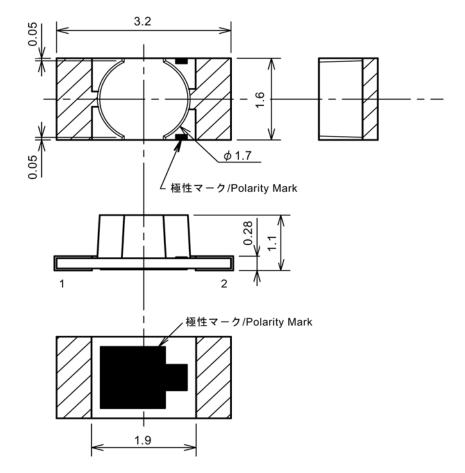
0

SHD00719BEK

100

Package (Unit: mm)

KLTFTN2K1100



- Pin name
 - 1: Anode
 - 2: Cathode

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